



德砚电子

DE YAN DIAN ZI

一体成型功率电感

Data Sheet

RoHS



ISO 9001
质量管理体系认证



ISO 14001
环境管理体系认证

Shenzhen Deyan Electronics Co., Ltd

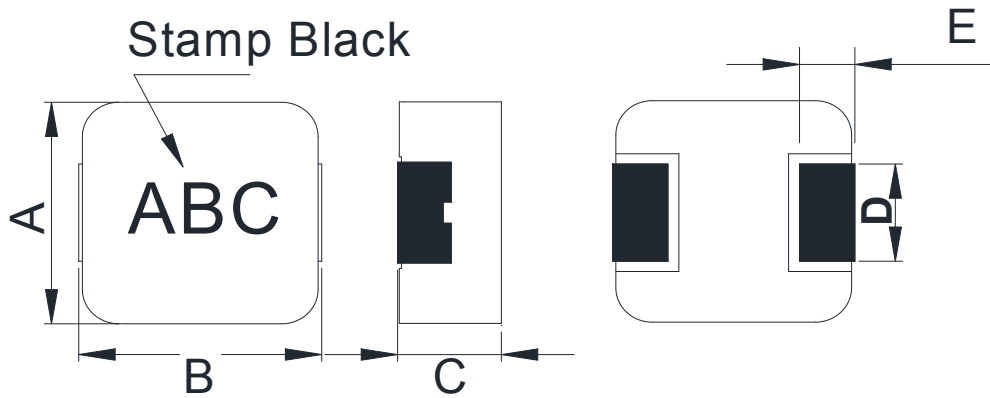
SPECIFICATION

			AMENDMENT RECORD			
SYMBOL	DATE	PAGE	CONTENTS	DWN. BY	CHK. BY	APP. BY
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SPECIFICATION

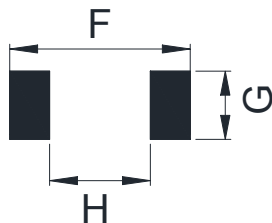
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		D0650HP-330MT		2024-05-08	--	01	1/5

1. DIMENSIONS (UNIT : mm)



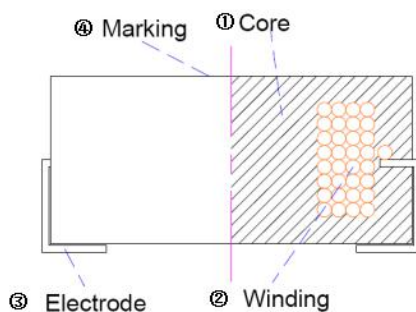
A	B	C	D	E
6.6±0.3	7.1 ±0.3	5.0 MAX	3.0 ±0.3	1.6 ±0.5

2. RECOMMENDED LAND PATTERN (UNIT: mm)



F	8.4 Ref.
G	3.5 Ref.
H	3.7 Ref.

3. STRUCTURE



No.	PARTS	MATERIAL
①	CORE	Alloy powder
②	WIRE	Self bonding polyamide-imide enameled Copper Wire
③	ELECTRODE	Cu
④	MARKING	INK

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4.CHARACTERISTICS

No.	P/N.	Inductance (μH)	Stamp	D.C.R. (mΩ) Max.	Saturation Current (A)		Temperature rise current(ΔT≤40℃) (A).	
					Typ	MAX	Typ	MAX
01	D0650HP-330MT	33±20%	330	200	3.0	2.5	2.3	2.0

* Testing instrument: Inductance HP 4284A or equivalent at 100KHz /1V..

D.C.R : TH2512B or equivalent. (Ta= 25℃)

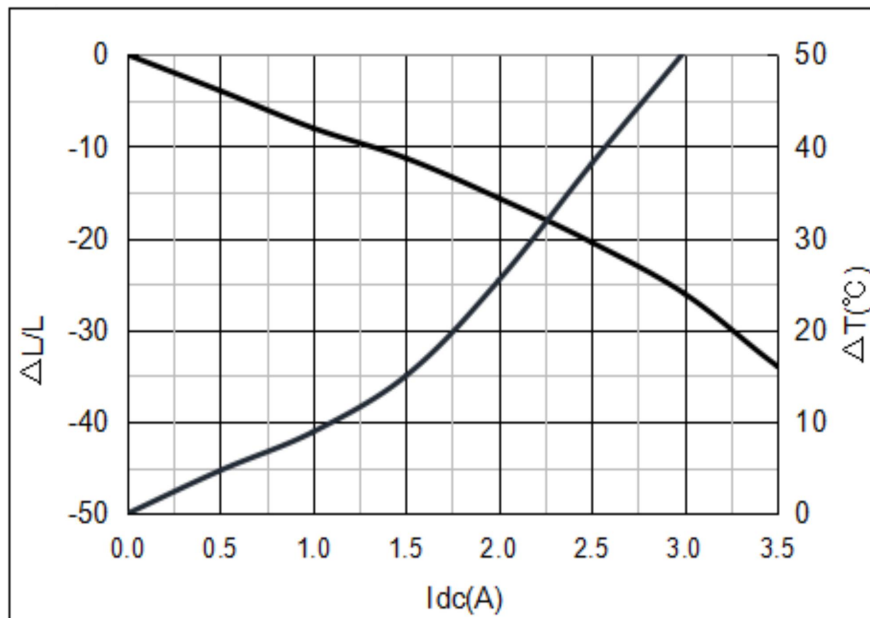
Saturation current: WK 3260B+3265B or equivalent.

* Saturation current: indicates the current when the inductance decrease to approximately 70% of initial value. (Ta=25℃)

* The temperature rise current value is the DC current value having temperature increase up to approximately 40℃(Ta=25℃)

* Absolute maximum voltage 30VDC

330 DC Bias & Temperature Characteristics



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5. GENERAL CHARACTERISTICS

* STANDARD TESTING CONDITIONS:

UNLESS OTHERWISE SPECIFIED, THE STANDARD RANGE OF ATMOSPHERIC CONDITIONS FOR MEASUREMENTS AND TESTS ARE AS FOLLOWS: AMBIENT TEMPERATURE: 15°C~35°C.

RELATIVE HUMIDITY : 25% ~85%. AIR PRESSURE : 86kPa ~106kPa.

IF THERE IS ANY DOUBT ABOUT THE RESULTS, MEASUREMENT SHALL BE MADE WITHIN THE FOLLOWING LIMITS: AMBIENT TEMPERATURE: 20°C±1°C. RELATIVE HUMIDITY: 63% ~67%.

AIR PRESSURE : 86kPa ~106kPa.

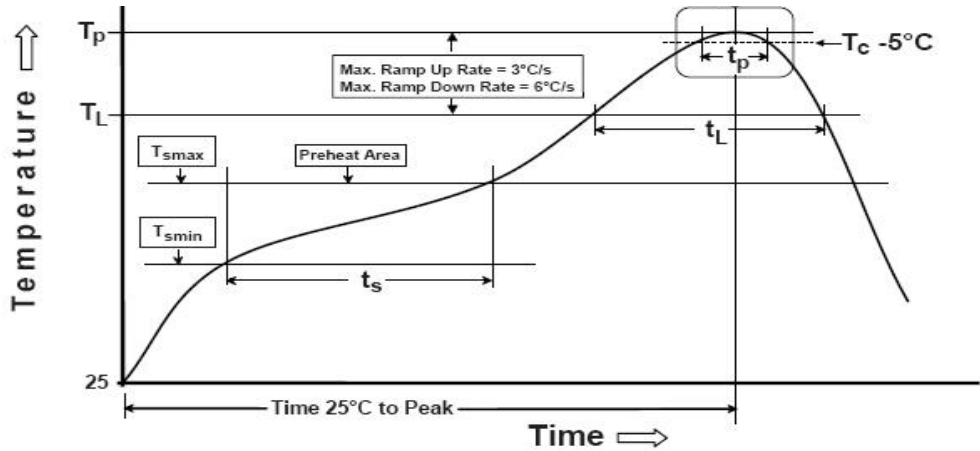
No.	ITEMS	CONDITIONS	SPECIFICATION
1	OPERATION TEMPERATURE STORAGE TEMPERATURE		-40 ~ + 125°C (INCLUDING COIL TEMPERATURE RISE) -40 ~ + 125°C
2	TEMPERATURE COEFFICIENT	-30 ~ +105°C	0 ~ 2000 ppm/°C
3	FIXING STRENGTH	SAMPLE IS PUSHED IN THREE DIRECTIONS OF X, Y AND Z WITH FORCE OF 5. 0N FOR 10±5 SECONDS. AFTER SOLDERING BETWEEN COPPER PLATE AND ELECTRODES.	NO ELECTRODE DETACHMENT.
4	RESISTANCE TO SOLDERING HEAT TEST	REFER TO THE SPEC "STD-001NP".	NO MECHANICAL BREAKAGE. DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
5	SOLDERABILITY TEST	IMMERSE THE ELECTRODE IN FLUX FOR 5 SECONDS. THEN DIP THE ELECTRODE INTO A SOLDERING BATH OF 245±5°C FOR 2±0.5 SECONDS.	OVER 95% OF THE SURFACE BEING IMMersed SHALL BE COVERED WITH NEW SOLDER UNIFORMLY.
6	VIBRATION TEST	AMPLITUDE: 1.5mm P-P FREQUENCY:10~55~10Hz (1 MINUTE PER CYCLE) DURATION: 1 HOUR IN EACH OF X, Y, Z AXIS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
7	HUMIDITY TEST	TEMPERATURE: 40°C±2°C HUMIDITY: 90%~95%RH DURATION: 96±4 HOURS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
8	THERMAL SHOCK TEST	20 CYCLES OF +105°C FOR 30 MINUTES, -40 °C FOR 30 MINUTES. CHARACTERISTICS ARE MEASURED AFTER THE AMBIENT AIR EXPOSURE OF 1 HOUR	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
9	HIGH TEMPERATURE STORAGE TEST	TEMPERATURE: 125°C±2°C DURATION: 96±4 HOURS	
10	LOW TEMPERATURE STORAGE TEST	TEMPERATURE: -40°C±3°C DURATION: 96±4 HOURS.	

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. Reflow profile for SMT components



Reflow is referred to standard IPC/ JEDEC J-STD-020D

Profile Feature		Lead(Pb) Free solder
Preheat and soak	·temperature Min.(T _{smin})	150°C
	·temperature Max.(T _{smax})	200°C
	·time(T _{smin} to T _{smax})(t _s)	60-120 Seconds
Average ramp up rate T _{smax} to T _p		3°C/Second Max.
Liquidous temperature (T _L)		217 °C
Time (T _L) maintained above T _L		60-150 seconds
Peak package body temperature (T _p)		Table2
Time (t _p)* within 5 °C of the specified classification temperature (T _c)		30* seconds
Average Ramp-down rate (T _p to T _L)		6 °C/second max
Time 25 °C to peak temperature		8 minutes max.

Table2. Pb-Free Process - Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350~2000	Volume mm ³ >2000
<1.6 mm	260°C	260°C	260°C
1.6mm- 2.5mm	260°C	250°C	245°C
>2.5 mm	250°C	245°C	245°C

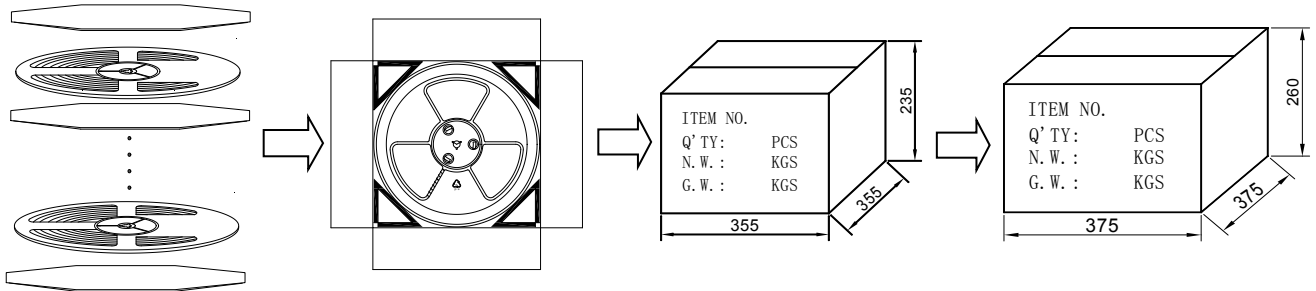
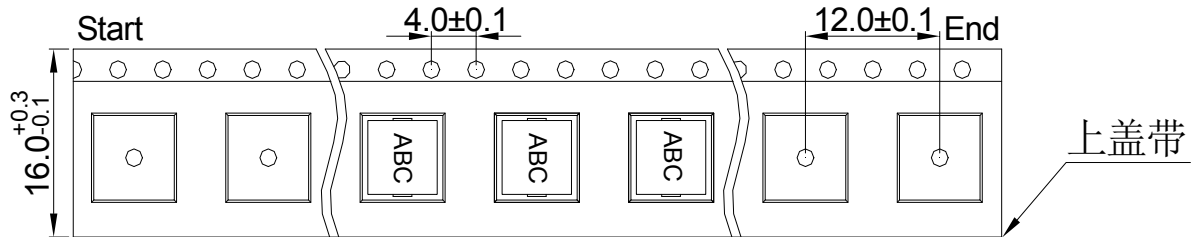
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7. PACKING

REFER TO STANDARD PACKING DRAWING. 1000PCS/R



REEL	1000PCS
BOX	8000PCS

8. NOTE

SOLDERING TIN PERIOD OF VALIDITY: SIX MONTHS
 STORAGE TEMPERATURE: 25°C±5°C
 COMPARATIVELY HUMIDITY: 35%--70%

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